2SC2497, 2SC2497A

Silicon NPN epitaxial planar type

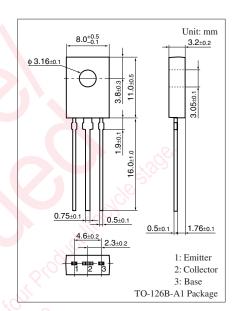
For low-frequency power amplification Complementary to 2SA1096, 2SC1096A

■ Features

- ullet High collector-emitter voltage (Base open) V_{CEO}
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Er	V_{CBO}	70	V	
Collector-emitter voltage	2SC2497	V_{CEO}	50	V
(Base open)	2SC2497A		60	
Emitter-base voltage (Coll	V_{EBO}	5	V	
Collector current	I_{C}	1.5	A	
Peak collector current	I_{CP}	3	A	
Collector power dissipation	P _C	1.2	W	
Junction temperature	T _j	150	°CO	
Storage temperature	T_{stg}	-55 to +150	°C	
				\sim



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emi	itter open)	V _{CBO}	$I_C = 1 \text{ mA}, I_E = 0$	70	0,		V
Collector-emitter voltage	2SC2497	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	50	O		V
(Base open)	2SC2497A	3	The sign of	60			
Collector-base cutoff current (E	mitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_E = 0$			1	μΑ
Collector-emitter cutoff current	(Base open)	I_{CEO}	$V_{CE} = 10 \text{ V}, I_{B} = 0$			100	μΑ
Emitter-base cutoff current (Collector open)		I_{EBO}	$V_{EB} = 5 \text{ V}, I_{C} = 0$			10	μΑ
Forward current transfer rat	io *1, 2	h_{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ A}$	80		220	_
Collector-emitter saturation	voltage	V _{CE(sat)}	$I_C = 1.5 \text{ A}, I_B = 0.15 \text{ A}$			1	V
Base-emitter saturation voltage		V _{BE(sat)}	$I_C = 1.5 \text{ A}, I_B = 0.15 \text{ A}$			1.5	V
Transition frequency		f_T	$V_{CB} = 5 \text{ V}, I_E = -0.5 \text{ A}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance		C _{ob}	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		35		pF
(Common base, input open	circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

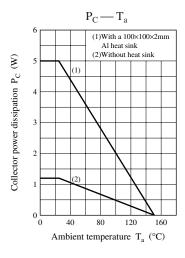
2. *1: Pulse measurement

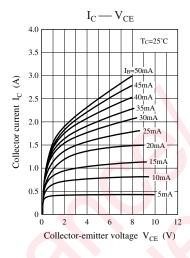
*2: Rank classification

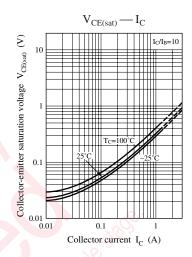
Rank	Q	R		
h_{FE}	80 to 160	120 to 220		

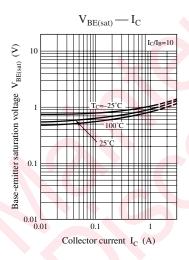
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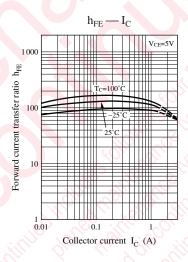
Panasonic

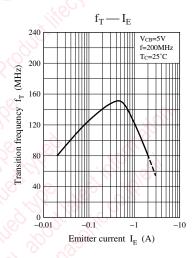


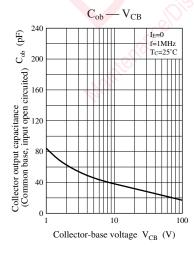


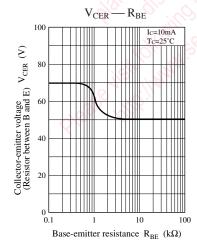


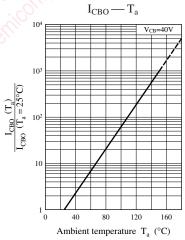




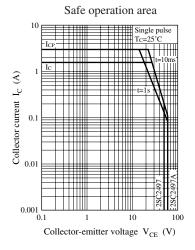








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